

N-Channel Enhancement Mode MOSFET

TDM3532

DESCRIPTION

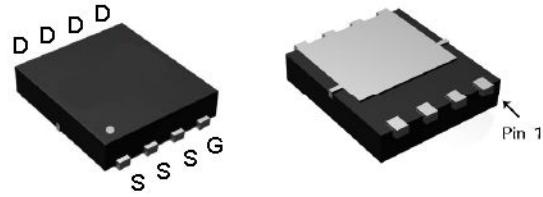
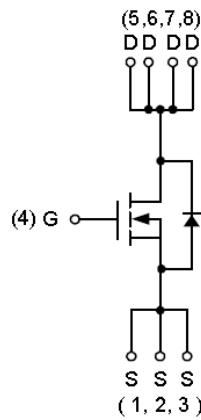
The TDM3532 uses advanced trench technology to provide excellent RDS(ON) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

- RDS(ON) < 3mΩ @ VGS=4.5V
- RDS(ON) < 1.9mΩ @ VGS=10V
- High Power and current handling capability
- Lead free product is available
- Surface Mount Package

Application

- PWM applications
- Load switch
- Power management



DFN5x6-8

ABSOLUTE MAXIMUM RATINGS
泰德半导体--提供样品，技术支持 手机13418601901 QQ409545144

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G S	±20	V
Diode Continuous Forward Current	I _S (T _c =25°C)	42.5	A
Drain Current @ Continuous (Note 1)	I _D (T _c =25°C)	131	A
	I _D (T _c =100°C)	124	A
Drain Current @ Current-Pulsed (Note 2)	I _{DM} (T _c =25°C)	160	A
Maximum Power Dissipation	P _D (T _c =25°C)	78	W
	P _D (T _c =100°C)	31	W
Drain Current @ Continuous (Note 3)	I _D (T _A =25°C)	28	A
	I _D (T _A =70°C)	22	A
Maximum Power Dissipation (Note 3)	P _D (T _A =25°C)	2.3	W
	P _D (T _A =70°C)	1.5	W
Thermal Resistance-Junction to Case	R _{θJC}	1.6	°C/W
Thermal Resistance,Junction-to-Ambient (Note 3)	R _{θJA} (t≤10s)	20	°C/W
	R _{θJA} (Steady State)	55	°C/W
Maximum Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55 To 150	°C
Avalanche Current, Single pulse (Note 4)	I _{AS} (L=0.1mH)	43	A
Avalanche Energy, Single pulse (Note 4)	E _{AS} (L=0.1mH)	92	mJ

N-Channel Enhancement Mode MOSFET

TDM3532

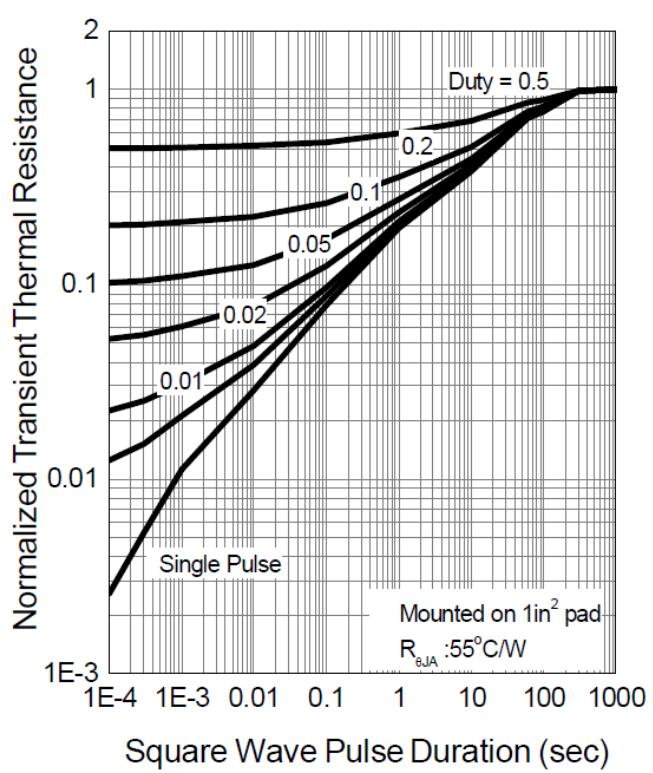
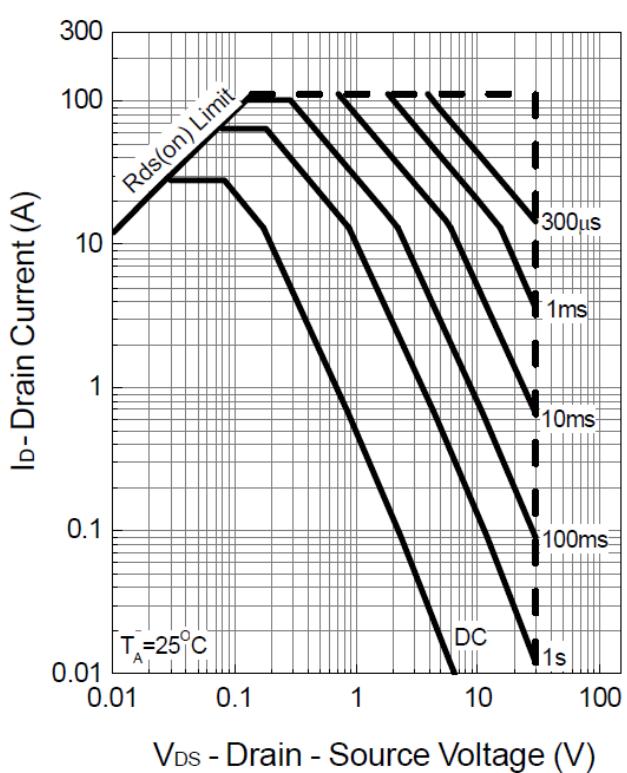
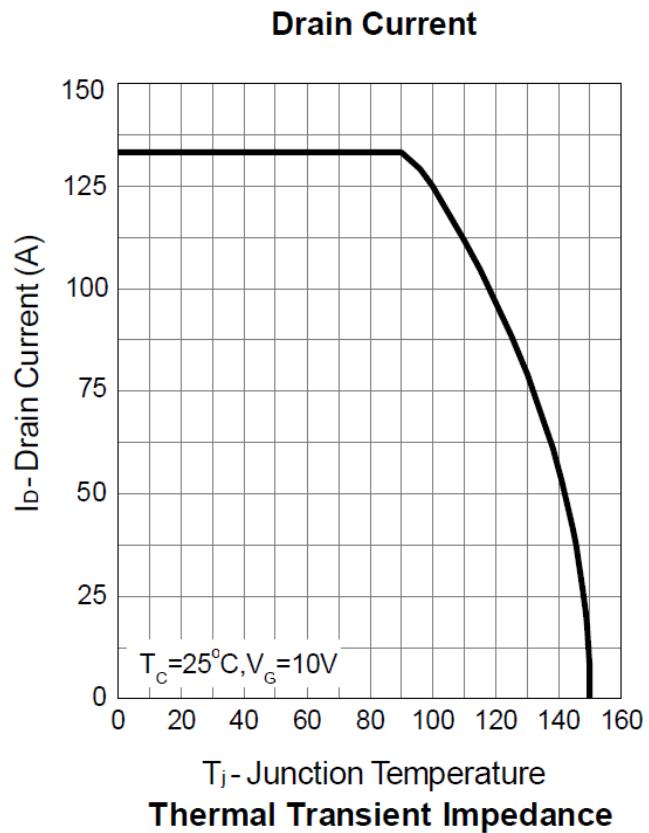
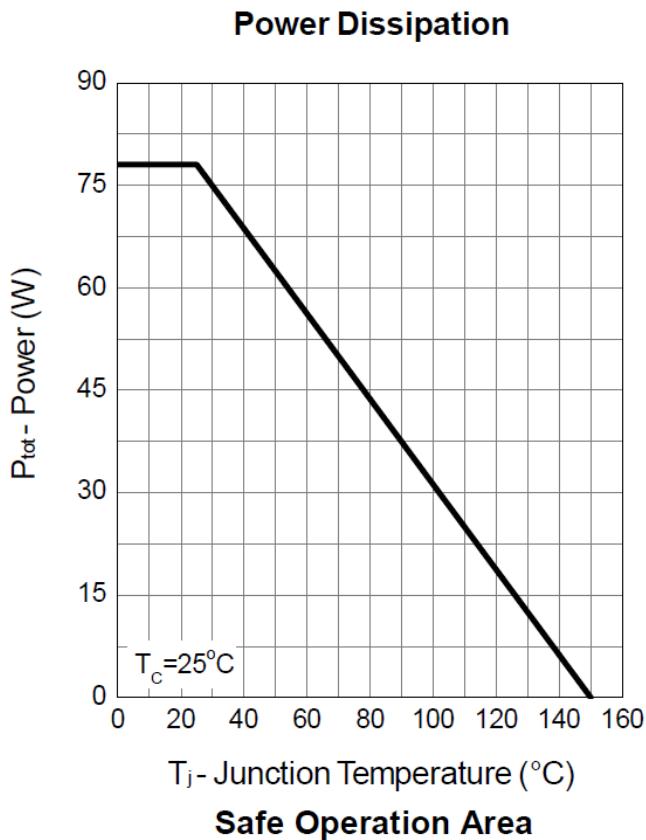
ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	30	-	-	V	
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=24\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA	
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA	
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1.3	1.6	2.3	V	
Drain-Source On-State Resistance (Note 5)	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=12\text{A}$	-	2.2	3	$\text{m}\Omega$	
		$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=20\text{A}$	-	1.5	1.9	$\text{m}\Omega$	
$\text{T}_J=125^\circ\text{C}$							
DYNAMIC CHARACTERISTICS (Note 6)							
Gate Resistance	R_G	$\text{V}_{\text{DS}}=0\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	0.9	2	Ω	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1.0\text{MHz}$	-	2800	3660	PF	
Output Capacitance	C_{oss}		-	1900	2485	PF	
Reverse Transfer Capacitance	C_{rss}		-	140	180	PF	
SWITCHING CHARACTERISTICS (Note 6)							
Turn-on Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DS}}=15\text{V}, \text{R}_L=15\Omega, \text{V}_{\text{GEN}}=10\text{V}, \text{R}_G=6\Omega, \text{I}_D=1\text{A}$	-	15.5	-	ns	
Turn-on Rise Time	t_r		-	11	-	ns	
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		-	35	-	ns	
Turn-Off Fall Time	t_f		-	40	-	ns	
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=15\text{V}, \text{I}_D=20\text{A}, \text{V}_{\text{GS}}=4.5\text{V}$	-	21.2	-	nC	
Gate-Source Charge	Q_{gs}		-	4.3	-	nC	
Gate-Drain Charge	Q_{gd}		-	8.3	-	nC	
Body Diode Reverse Recovery Time	T_{rr}	$\text{I}_F=20\text{A}, \frac{d\text{I}}{dt}=100\text{A}/\mu\text{s}$	-	50	-	ns	
Body Diode Reverse Recovery Charge	Q_{rr}		-	45	-	nC	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Diode Forward Voltage (Note 5)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=20\text{A}$	-	0.8	1.1	V	

NOTES:

1. continue current is limited by bonding wire.
2. Pulse width limited by max. junction temperature.
3. R_{OJA} steady state $t=999\text{s}$.
4. UIS tested and pulse width limited by maximum junction temperature 150°C
5. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
6. Guaranteed by design, not subject to production testing

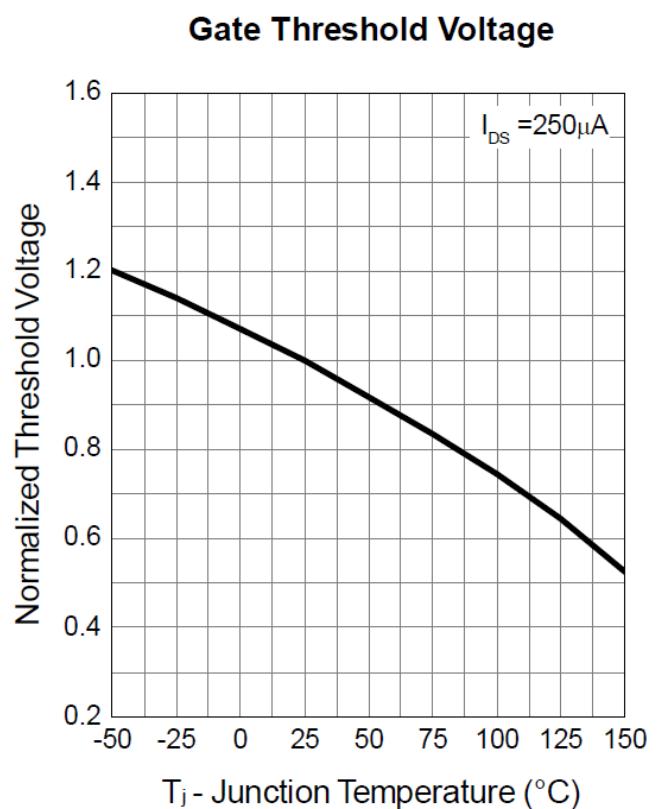
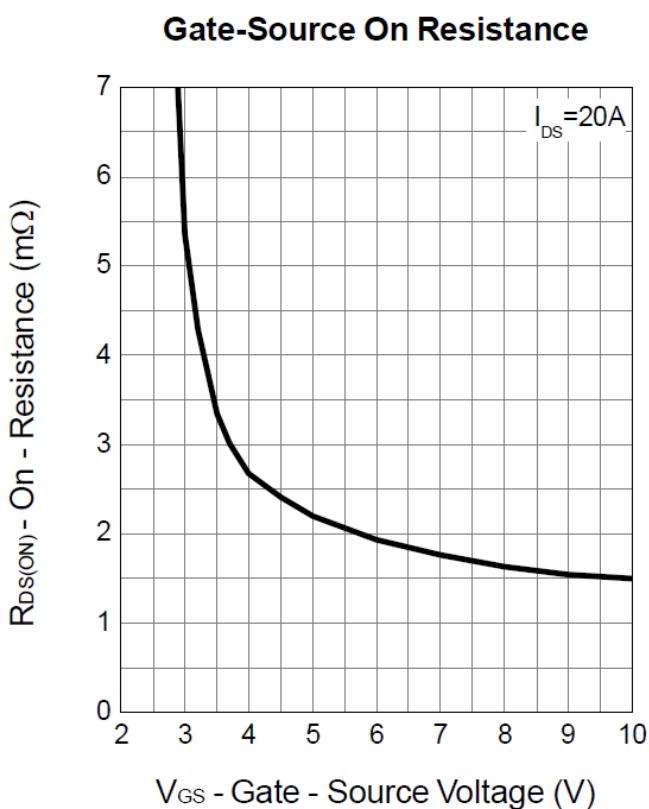
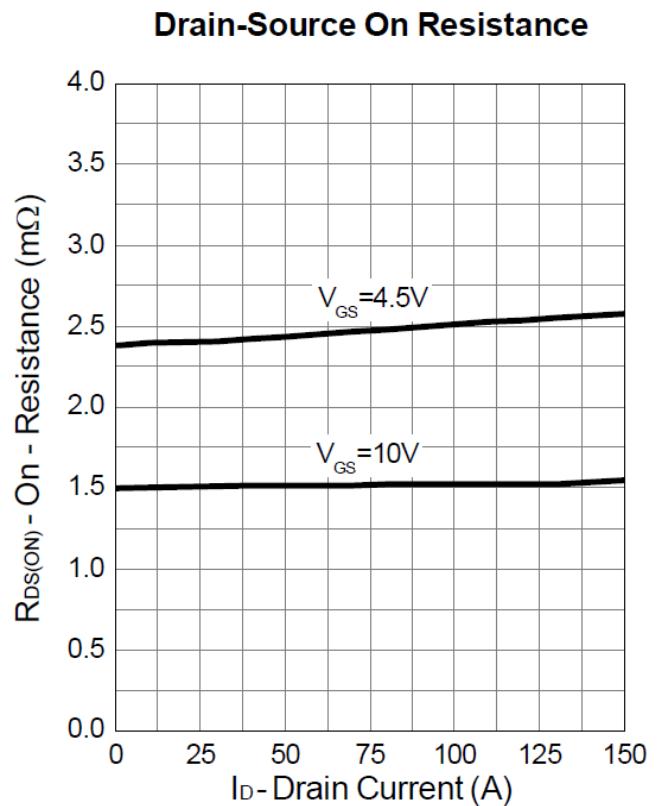
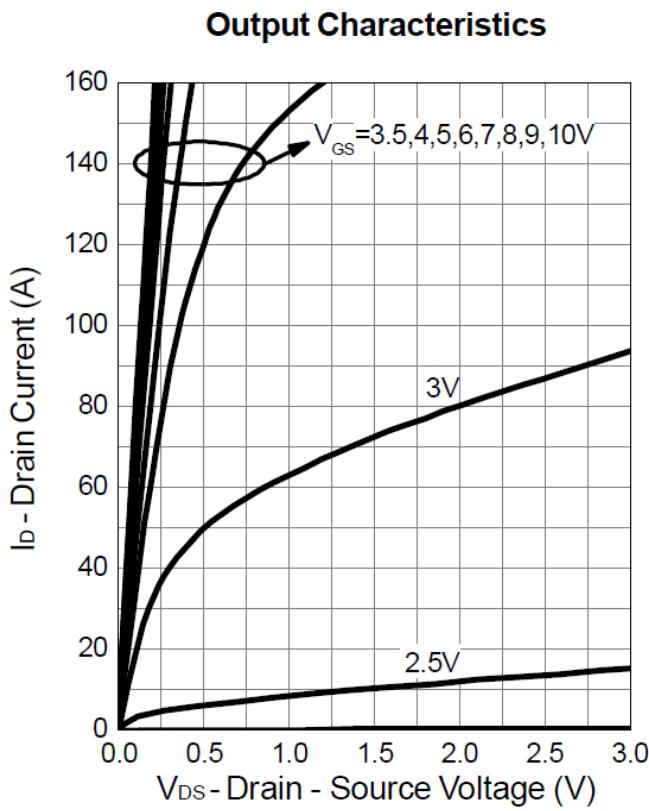
Typical Operating Characteristics



N-Channel Enhancement Mode MOSFET

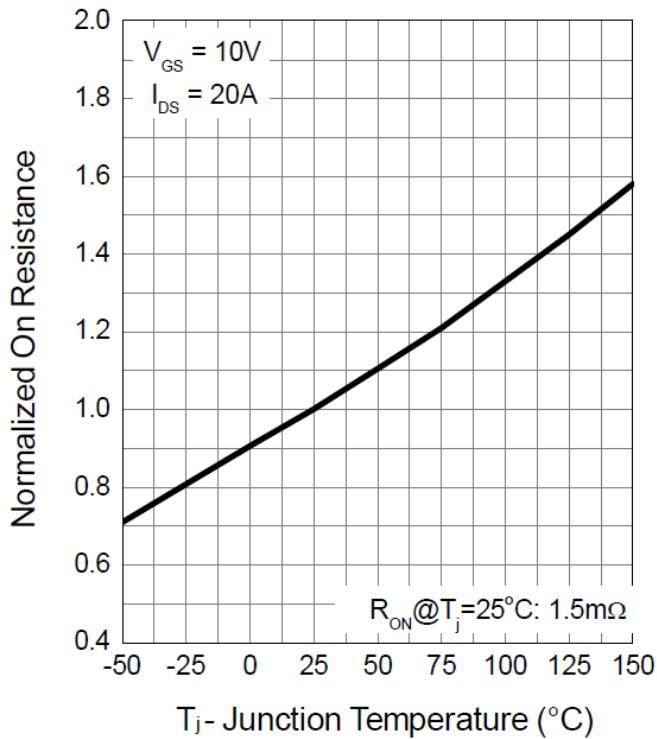
TDM3532

Typical Operating Characteristics(Cont.)

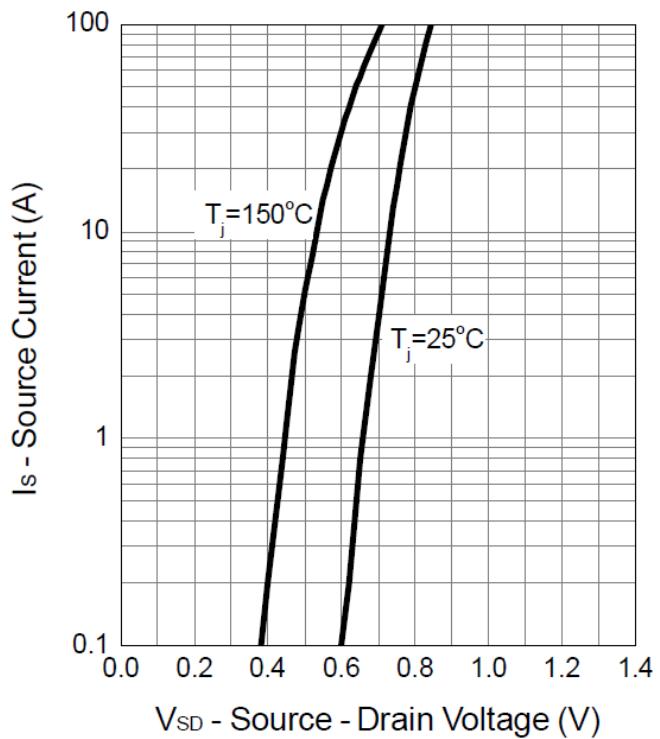


Typical Operating Characteristics (Cont.)

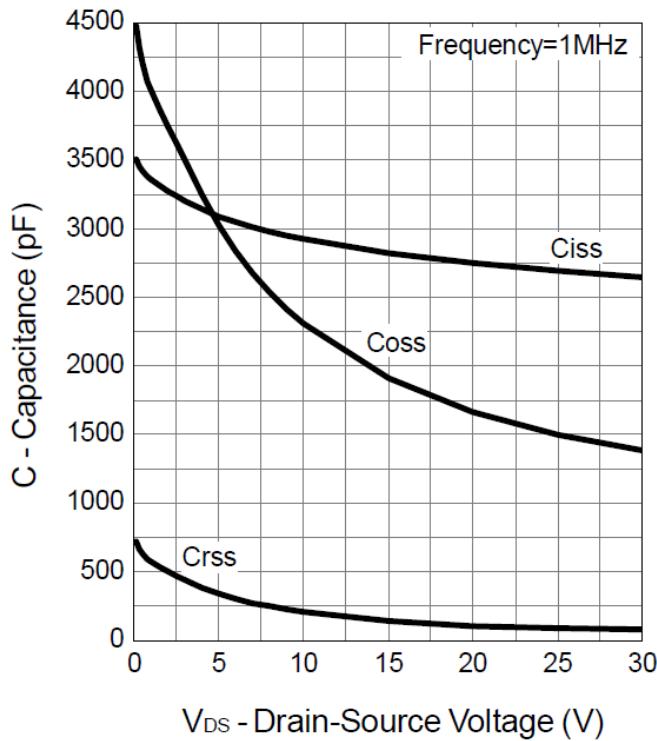
Drain-Source On Resistance



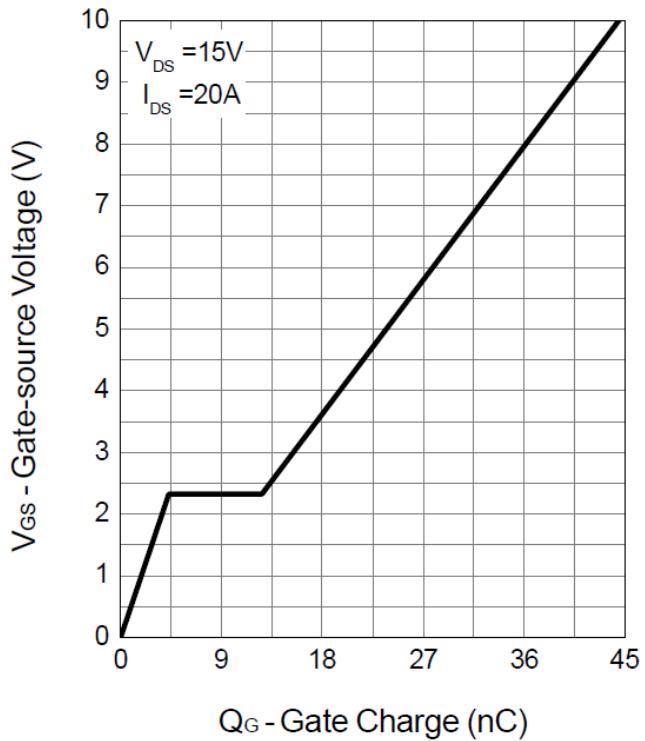
Source-Drain Diode Forward

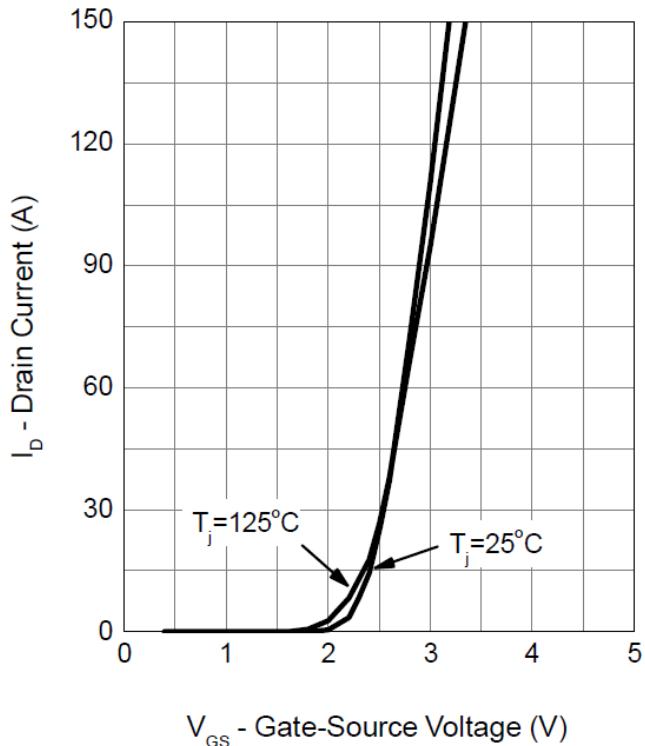


Capacitance



Gate Charge



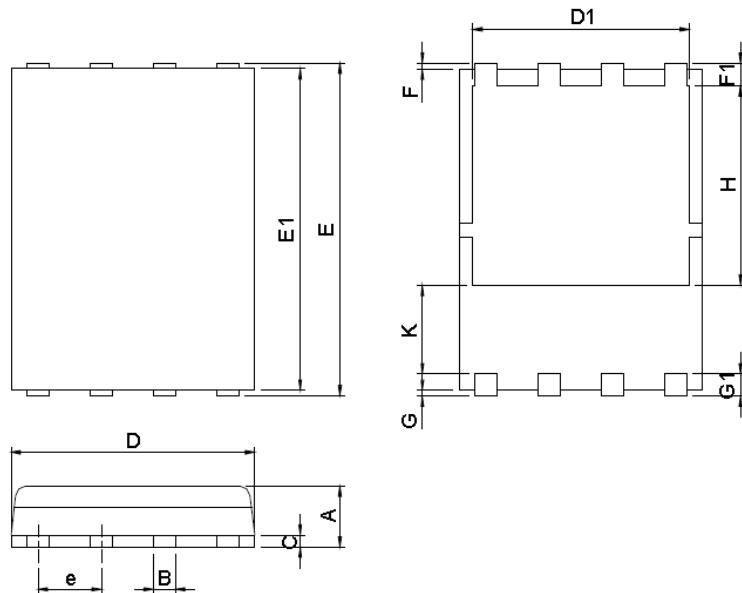
Typical Operating Characteristics (Cont.)**Transfer Characteristics**

N-Channel Enhancement Mode MOSFET

TDM3532

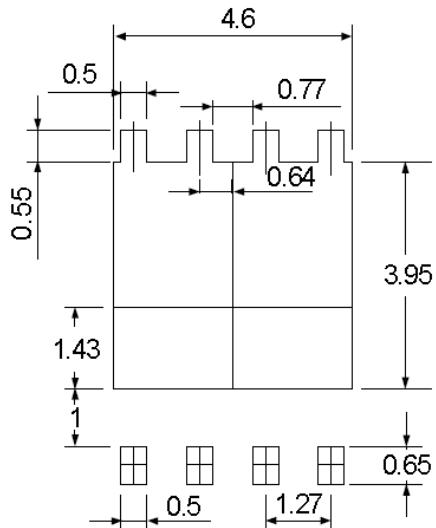
Package Information

DFN5*6-8 Package



SYMBOL	DFN5x6-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-

RECOMMENDED LAND PATTERN



UNIT: mm

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions.
Mold flash or protrusions shall not exceed 10 mil.

Design Notes